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84	BRS	1	"5849607".PN.	USPAT	2002/05/21 21:30
85	BRS	1	"5847929".PN.	USPAT	2002/05/21 21:30
86	BRS	1	"5840599".PN.	USPAT	2002/05/21 21:30
87	BRS	1	"5773313".PN.	USPAT	2002/05/21 21:31
88	BRS	1	"5729049".PN.	USPAT	2002/05/21 21:32
89	BRS	1	"5677566".PN.	USPAT	2002/05/21 21:32
90	BRS	1	"5674785".PN.	USPAT	2002/05/21 21:32
91	BRS	1	"5554886".PN.	USPAT	2002/05/21 21:32
92	BRS	1	"5483024".PN.	USPAT	2002/05/21 21:33
93	BRS	1	"5434105".PN.	USPAT	2002/05/21 21:33
94	BRS	1	"5418189".PN.	USPAT	2002/05/21 21:33
95	BRS	1	"5286679".PN.	USPAT	2002/05/21 21:33
96	BRS	1	"6326700"	USPAT	2002/05/21 22:21
97	BRS	1	"5977624".PN.	USPAT	2002/05/21 22:21
98	BRS	1	"6150730".PN.	USPAT	2002/05/21 22:21
99	BRS	1	"6177721".PN.	USPAT	2002/05/21 22:21
100	BRS	1	"6218731".PN.	USPAT	2002/05/21 22:21
101	BRS	1	"6252298".PN.	USPAT	2002/05/21 22:22
102	BRS	0	6071757.uref. and heat near sink and dielectric near (layer or film)	USPAT	2002/05/21 22:33
103	BRS	1	6071757.uref.	USPAT	2002/05/21 22:33
104	BRS	3	"6071757"	USPAT	2002/05/21 22:34
105	BRS	7	"5977629"	USPAT	2002/05/21 22:34



Creation date: 05-06-2004  
Indexing Officer: DBAGUYO - DAVE BAGUYO  
Team: OIPEBackFileIndexing  
Dossier: 09930295

Legal Date: 06-03-2002

No.	Doccode	Number of pages
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Total number of pages: 10

Remarks:

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